

REV	MODIFICATION	DATE	DRAW
B	EN-04-0419	04.14.04"	Aaron
C	EN-04-0505	05.12.04"	Aaron
D	EN-05-0902	09.02.05"	Stacey

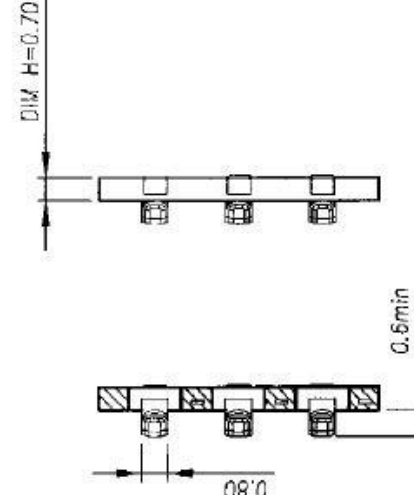
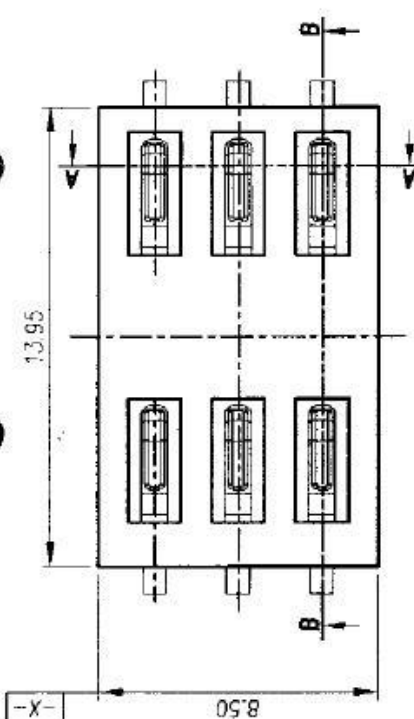
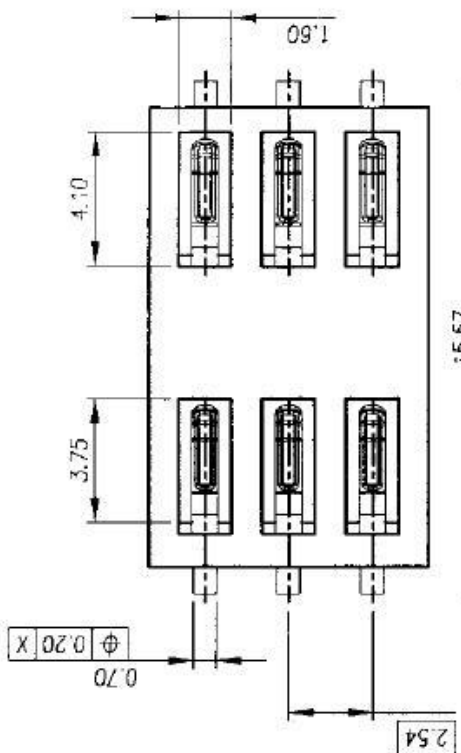
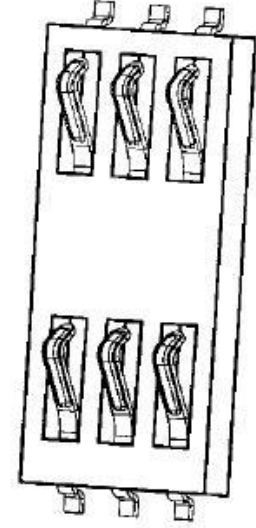
NOTES:

- 1) Material :
Housing : Thermoplastic UL94V-0
Contact : BERYLLIUM C17200R-H,T=0.10mm
- 2) Plating :
Contact Plating - Gold over 45u" MIN.Nickel
Solder Tail Plating - Gold over 45u" MIN.Nickel
- 3) Contact Forces :
Max. 0.5 N For 0.65mm Contact Deflection.
Min. 0.25 N For 0.65mm Contact Deflection.
- 4) Order Information :
SIMMP-006XXBXX2

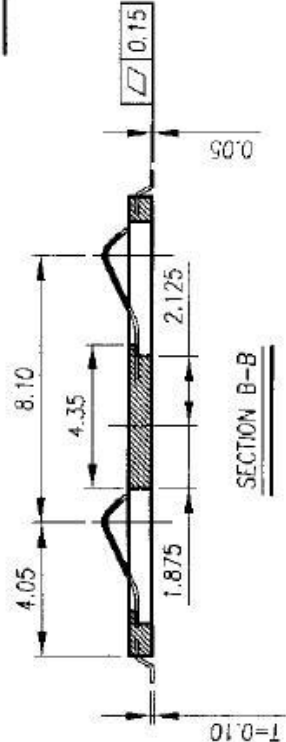
PLATING
30 : GOLD PLATING 30u"

0 : TAPE REEL
1 : TUBE

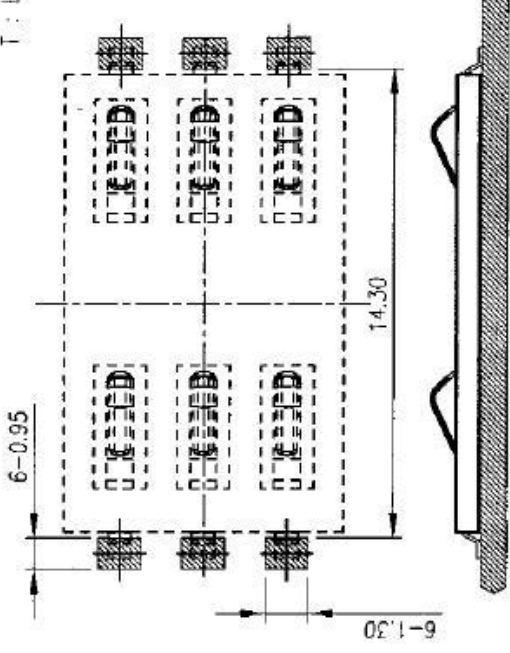
0 : TIN/LEAD PLATING
1 : LEAD FREE



SECTION A-A



SECTION B-B



P.C.B. LAYOUT (TOP VIEW)

DIMENSION IN mm [inch]	PROD. SPEC. SP0052	CUSTOMER DRAWING
TOLERANCE UNLESS OTHERWISE SPECIFIED	PWG. SPEC. PPP-SIM-002	Subscriber Identify Module Card Simple Style Conn. 6 Pin Same Direction Type 0.70mm
.X'±0.30	APPROVE <i>PP/15</i>	FILE NO. KFP-052
.XX'±0.20	CHECK	DWG NO. SIMMP-006XXBXX2
.XXX'±0.10	DRAW <i>Shen</i>	PROJ. SHEET 1
		SCALE 4:1 REV D
		SIZE A4